

What is claimed is:

1. A structure for expanding thermal conduction performance of a heat sink, comprising:

5 a bottom plate, having a bottom receiving chamber recessed from a top surface thereof;

a top plate, having a top receiving chamber recessed from a bottom surface thereof, wherein the top and bottom receiving chambers are aligned with each other, and the top plate and the bottom plate are covered by each other to form a planar shell, wherein the top and bottom receiving chambers are filled  
10 with work fluid;

a hollow filling tube embedded in a sidewall of the planar shell, the hollow filling tube being in fluid communication with the top and bottom receiving chambers, the filling tube has one sealed end distal to the planar shell;

a wick structure attached to the top and bottom plates within the top and  
15 bottom receiving chambers; and

at least one hollow thermal expansion conductor, wherein one end of the thermal expansion conductor is inserted into the planar shell, and the other end thereof extends outside of the planar shell, such that the thermal expansion conductor is in fluid communication with the top and bottom  
20 receiving chambers.

2. The structure as claimed in Claim 1, further comprising a plurality of supporting columns extending from the top surface of the bottom plate to the bottom surface of the top plate.

3. The switch as claimed in Claim 1, wherein the thermal expansion  
25 conductor includes a heat plate.

4. The structure as claimed in Claim 1, wherein the thermal expansion conductor includes a columnar heat pipe.

5. The structure as claimed in claim 1, wherein the thermal expansion conductor includes a tubular heat pipe.

6. The structure as claimed in Claim 5, further comprising a plurality of fins through which the tubular heat pipe penetrate through.

7. The structure as claimed in Claim 1, wherein a proximal end of the thermal expansion conductor is embedded in the planar shell between the top  
5 and bottom plates, and the other end thereof extends outside of the planar shell.

8. The structure as Claim 1, wherein the thermal expansion conductor is at least partially embedded in the bottom plate.

9. The structure as Claim 1, wherein the thermal expansion conductor is  
10 at least partially embedded in the top plate.